(42)—mounted on saidthe substrate, and one or more electrical connections (39,44,49) made to saidthe component(s)—(42). The insulating substrate—(34) closes the open end (37) of the metal canister—(36) so that the metal canister and insulating substrate (34) together form a housing—(32) for one or more of saidthe components—(42) mounted on the substrate (34). The insulating substrate—(34) acts as a circuit board to carry saidthe electrical connections from saidthe component(s) externally of the housing—(32). The canister—(36) has at least one optical port—(38) by which optical radiation—(45) may be transmitted into and/or out of saidthe housing—(32).

Figure 1

In The Claims

Please amend the claims as follows:

- 1. (Amended) An optoelectronic device (30,50,60,70,80,90), comprising an open-ended metal canister (36,56,66,76,86), an insulating substrate (34,54,64,74,84,94), at least one optoelectronic component (42,82,92) mounted on said substrate, and one or more electrical connections (39,44,49,79,89,109) made to said component(s) (42,82,92), wherein:
- the insulating substrate (34,54,64,74,84,94) closes the open end-(37) of the metal canister (36,56,66,76,86) so that the metal canister and insulating substrate (34,54,64, 74,84,94) together form a housing (32,52,62,72,82,92) for one or more of said components mounted on the substrate;
- the insulating substrate (34,54,64,74,84,94) acts as a circuit board to carry said electrical connections from said component(s) externally of the housing (32,52,62,72,82,92); and
- the canister— (36,56,66,76,86) has at least one optical port

(38,58,68,78,88,98) by which optical radiation (45,55,65,75,85) may be transmitted into and/or out of said housing (32,52,62,72,82,92).

- 2. (Amended) An optoelectronic device (30,50,60,70,80,90) as claimed in Claim 1, in which the housing (32,52,62,72,82,92) is hermetically sealed.
- 3. (Amended) An optoelectronic device (30,50,70,80) as claimed in Claim 1 or Claim 2, wherein an said optical port includes an optical window (38,58,78,88).
- 4. (Amended) An optoelectronic device (60) as claimed in Claim 1-or Claim 2, wherein said in which an optical port includes a receptacle (68) for an optical component (61).
- 5. (Amended) An optoelectronic device (30) as claimed in any preceding claim 1, whereinin which at least one said electrical connection includes at least one via (49,109) through said insulating substrate (34).
- 6. (Amended) An optoelectronic device (90) as claimed in Claim 5, in which said via (109) extends to a side (97) of the substrate (94) opposite from a side (93) of the substrate (94) that closes the open end (107) of the canister (96).
- 7. (Amended) An optoelectronic device (30) as claimed in Claim 6, in which at least one wherein said electrical connection includes a track-(44) on or within said substrate (34) that extends towards an edge-(47) of said substrate.
- 8. (Amended) An optoelectronic device (30) as claimed in any preceding claim 1, in which the wherein said substrate (34) includes a multilayer printed circuit board (36) for making electrical connections internally and/or externally of said housing (32).

- 9. (Amended) An optoelectronic device (30) as claimed in any preceding claim 1, wherein said in which the substrate (36) includes a printed metallic layer (35) to which the open end (37) of the canister (36) is bonded.
- 10. (Amended) An optoelectronic device (30,50,60,70,90) as claimed in any preceding claim 1, in which the wherein said substrate is a ceramic substrate (34,54,64,74,94).
- 11. (Amended) An optoelectronic device (80) as claimed in any of Claims 1-to 9, in which the, wherein said substrate is a flex substrate (84).